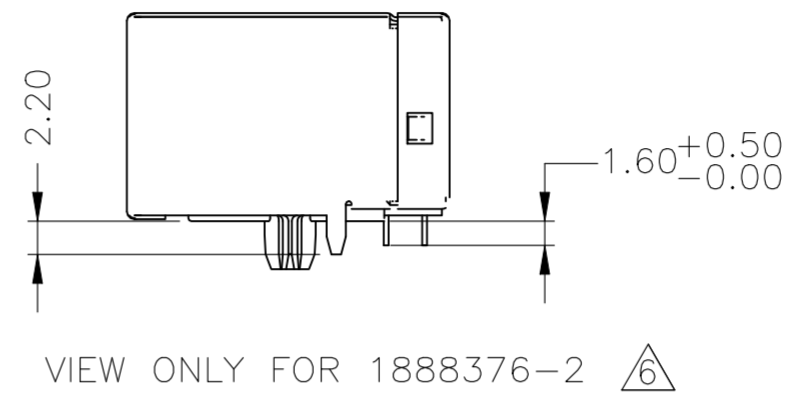
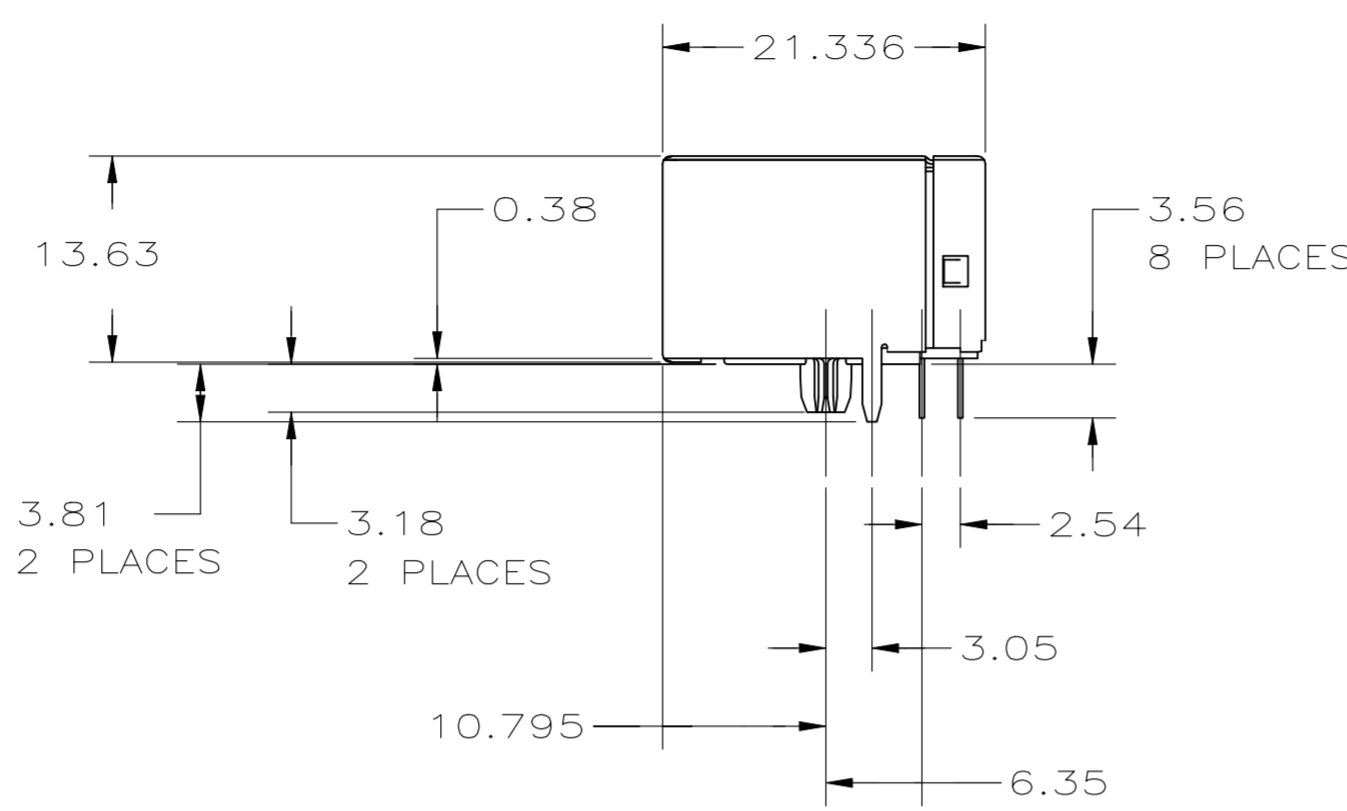
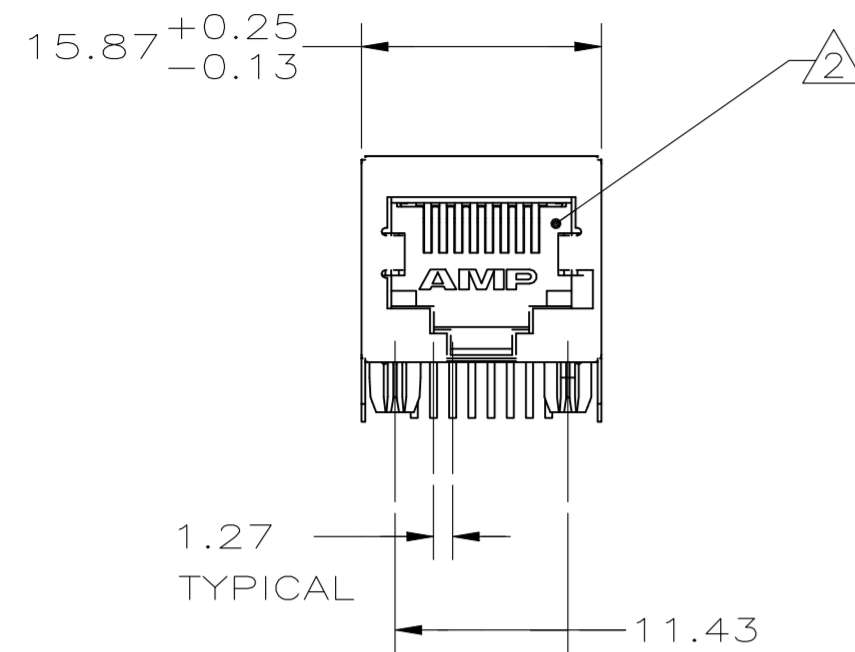
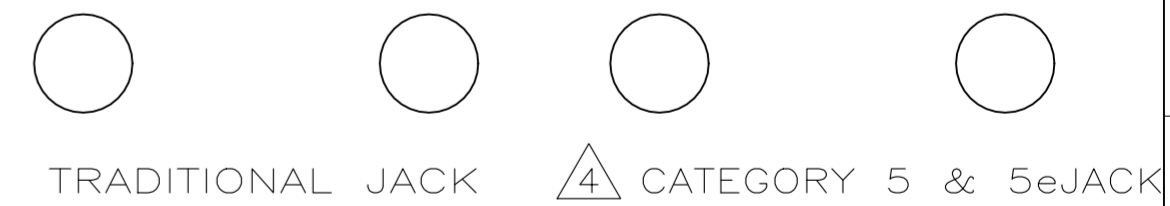
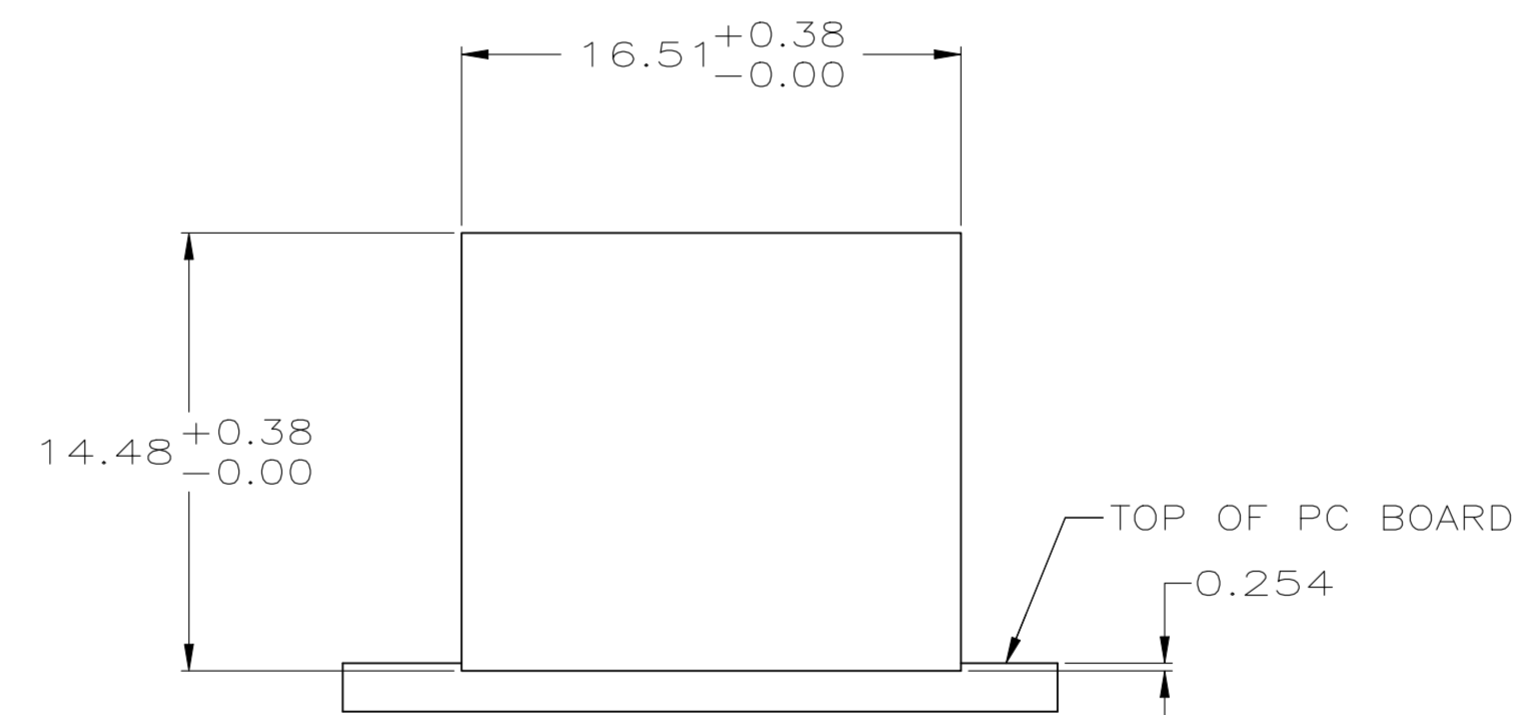
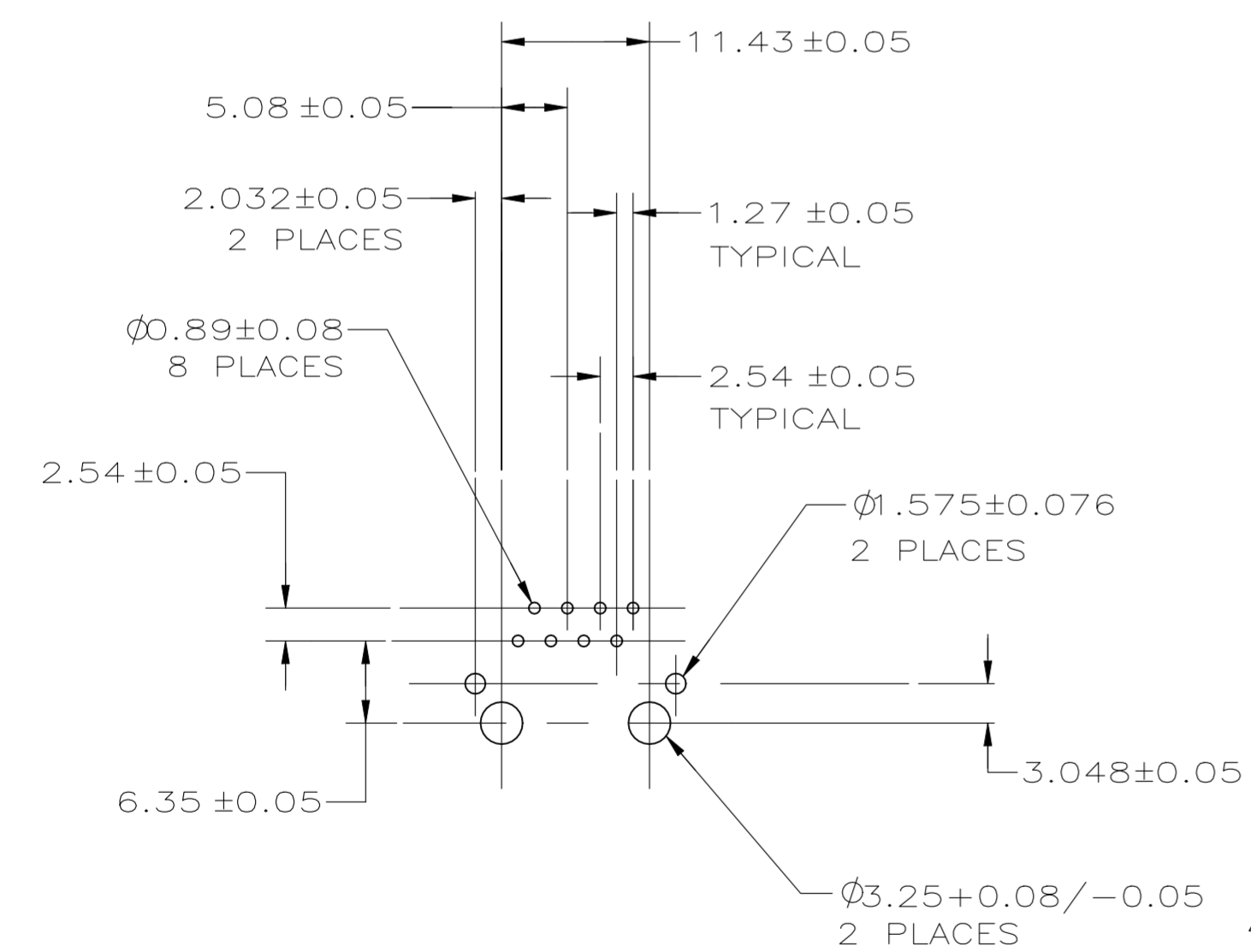


P	LTR	DESCRIPTION	DATE	DWN	APVD
C1	ECR-19-014657		13DEC2020	RR	SZ



- ⚠ MATERIAL: HOUSING HIGH TEMPERATURE NYLON, TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [.000050] MINIMUM SATIN NICKEL WITH 2.03 μm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS
- ⚠ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
- ⚠ CAUTION: CATEGORY 5 JACK SOLDER TAIL POSITIONS DO NOT FOLLOW SAME NUMBER SEQUENCE AS THAT OF TRADITIONAL JACKS.
- ⚠ USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- ⚠ SHORT PIN TYPE, ONLY FOR 1888376-2
- ⚠ MATERIAL: LCP, BLACK, UL94V-0. LEAD FREE IR REFLOW PROCESS COMPATIBLE.
TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [.000050] MINIMUM SATIN NICKEL WITH 2.03 μm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS



SUGGESTED PC BOARD LAYOUT COMPONENT SIDE

SUGGESTED PANEL CUTOUT SCALE 4:1

⚠	TAPE&REEL	⚠ 1888376-2
⚠	TRAY	1888376-1
MATERIAL	PACKAGE	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. PITTS/L.A.MAYER 01JUNE2005	TE Connectivity	
DIMENSIONS: mm		CHK J.WESTMAN 01JUNE2005	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.FLICKINGER 01JUNE2005	PRODUCT SPEC	
0 PLC ± -		108-1163	APPLICATION SPEC	
1 PLC ± -		114-2048	SIZE	CAGE CODE
2 PLC ± 0.254[.01]		WEIGHT	A2	00779
3 PLC ± 0.127[.005]		CUSTOMER DRAWING	SCALE	2:1
4 PLC ± -			SHEET	1 of 1
ANGLES ± -			REV	C1
FINISH				
SEE NOTE 1 & 8				